L	Hits	Search Text	DB	Time stamp
Number 17	196	(argon with physical) and nitrogen and	USPAT;	2004/04/29
10	26	sputtering	US-PGPUB USPAT;	14:26 2004/04/29
18	26	((argon with physical) and nitrogen and sputtering) and (RF with sputter\$3)	US-PGPUB	14:27
19	17	(((argon with physical) and nitrogen and	USPAT;	2004/04/29
		sputtering) and (RF with sputter\$3)) and @ad<20010828	US-PGPUB	14:34
22	3602	argon and nitrogen and (sputtering same	USPAT;	2004/04/29
		(etching or cleaning))	US-PGPUB	15:15
20	21	argon and nitrogen and (sputtering same (etching or cleaning))	EPO; DERWENT	2004/04/29
23	2767	(argon and nitrogen and (sputtering same	USPAT;	2004/04/29
		(etching or cleaning))) and @ad<20010828	US-PGPUB	15:17
24	2161	((argon and nitrogen and (sputtering same (etching or cleaning))) and @ad<20010828)	USPAT; US-PGPUB	2004/04/29 15:16
		and (hole or opening or trench or recess	05 10102	10.10
		or aperture or via)		2004/04/20
25	42	(physical with argon) and (((argon and nitrogen and (sputtering same (etching or	USPAT; US-PGPUB	2004/04/29
		cleaning))) and @ad<20010828) and (hole		
		or opening or trench or recess or		
26	1391	aperture or via)) argon and nitrogen and (RF with	USPAT;	2004/04/29
		sputtering) and (etching or cleaning)	US-PGPUB	15:20
27	833	(argon same nitrogen) and (RF with	USPAT; US-PGPUB	2004/04/29
28	628	sputtering) and (etching or cleaning) ((argon same nitrogen) and (RF with	USPAT;	2004/04/29
		sputtering) and (etching or cleaning))	US-PGPUB	15:26
		and (hole or opening or trench or recess		
29	470	or aperture or via) (((argon same nitrogen) and (RF with	USPAT;	2004/04/29
		sputtering) and (etching or cleaning))	US-PGPUB	15:26
		and (hole or opening or trench or recess or aperture or via)) and @ad<20010828		
30	2	(argon with physical) and (((argon same	USPAT;	2004/04/29
		nitrogen) and (RF with sputtering) and	US-PGPUB	15:17
		(etching or cleaning)) and (hole or opening or trench or recess or aperture		
		or via)) and @ad<20010828)		
31	1	argon and nitrogen and (RF with	EPO; JPO; DERWENT	2004/04/29
32	8	sputtering) and (etching or cleaning) argon and nitrogen and bombardment and	EPO; JPO;	2004/04/29
		(etching or cleaning)	DERWENT	15:24
33	2	helium and nitrogen and bombardment and (etching or cleaning)	EPO; JPO; DERWENT	2004/04/29 15:25
34	1009	helium and nitrogen and bombardment and	USPAT;	2004/04/29
		(etching or cleaning)	US-PGPUB	15:25
35	851	(helium and nitrogen and bombardment and (etching or cleaning)) and (hole or	USPAT; US-PGPUB	2004/04/29 15:26
		opening or trench or recess or aperture	32 232 32	-3.20
26	650	or via)	HCDATT-	2004/04/29
36	653	((helium and nitrogen and bombardment and (etching or cleaning)) and (hole or	USPAT; US-PGPUB	15:26
		opening or trench or recess or aperture		
37	291	or via)) and @ad<20010828 (((helium and nitrogen and bombardment	USPAT;	2004/04/29
3'	291	and (etching or cleaning)) and (hole or	US-PGPUB	15:27
		opening or trench or recess or aperture		
38	0	or via)) and @ad<20010828) and organic ((((helium and nitrogen and bombardment	USPAT;	2004/04/29
		and (etching or cleaning)) and (hole or	US-PGPUB	15:27
		opening or trench or recess or aperture		
		or via)) and @ad<20010828) and organic) and (chemcial with nitrogen)		
39	5	((((helium and nitrogen and bombardment	USPAT;	2004/04/29
		and (etching or cleaning)) and (hole or	US-PGPUB	15:27
1		opening or trench or recess or aperture or via)) and @ad<20010828) and organic)		
		and (physical with helium)	<u> </u>]